

DisplayPort 1:1 Buffer

FEATURES

- Supports Data Rates up to 2.7 Gbps
- Supports Dual-Mode DisplayPort
- Output Waveform Mimics Input Waveform Characteristics
- Enhanced ESD: 12 KV on all pins
- Enhanced Commercial Temperature Range: 0°C to 85°C
- 36 Pin 6 × 6 QFN Package

APPLICATIONS

- Personal Computer Market
 - Desktop PC
 - Notebook PC
 - Docking Station
 - Standalone Video Card

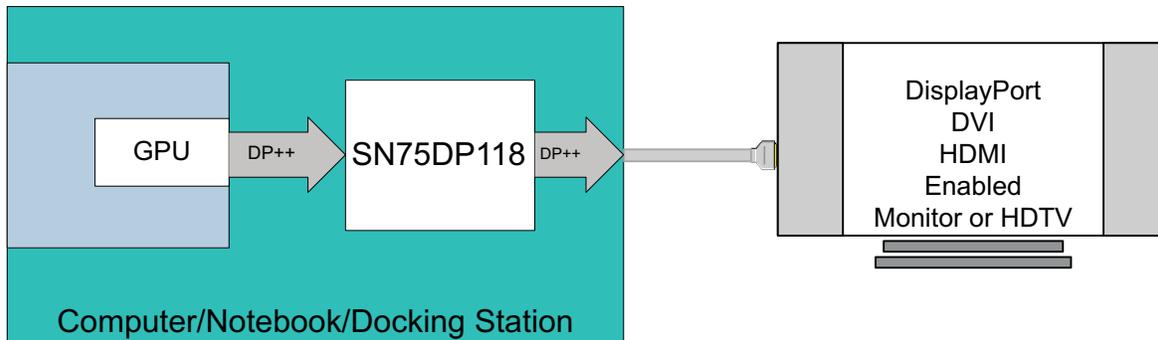
DESCRIPTION

The SN75DP118 is a one Dual-Mode DisplayPort input to one Dual-Mode DisplayPort output. The output follows the input signal in a manner that provides the highest level of signal integrity while supporting the EMI benefits of spread spectrum clocking. The SN75DP118 data rates of up to 2.7 Gbps through each link for a total throughput of up to 10.8 Gbps can be realized.

In addition to the DisplayPort high speed signal lines, the SN75DP118 also supports the Hot Plug Detect (HPD) and Cable Adapter Detect (CAD) channels.

The SN75DP118 is characterized for operation over ambient air temperature of 0°C to 85°C.

TYPICAL APPLICATION

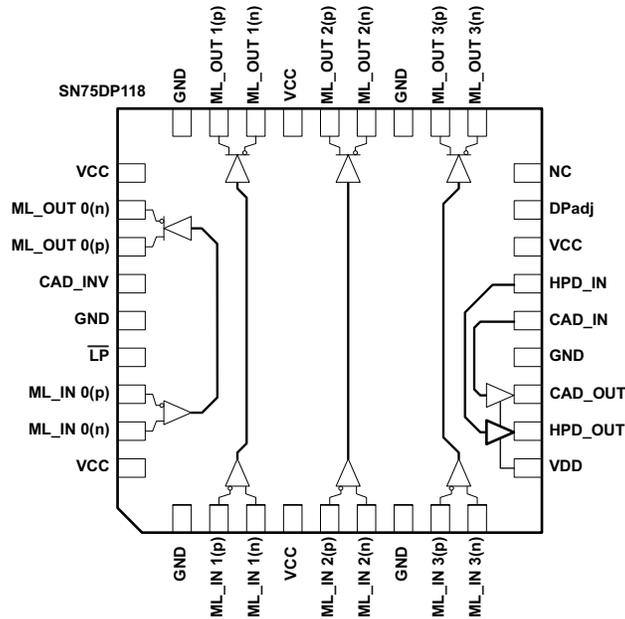


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

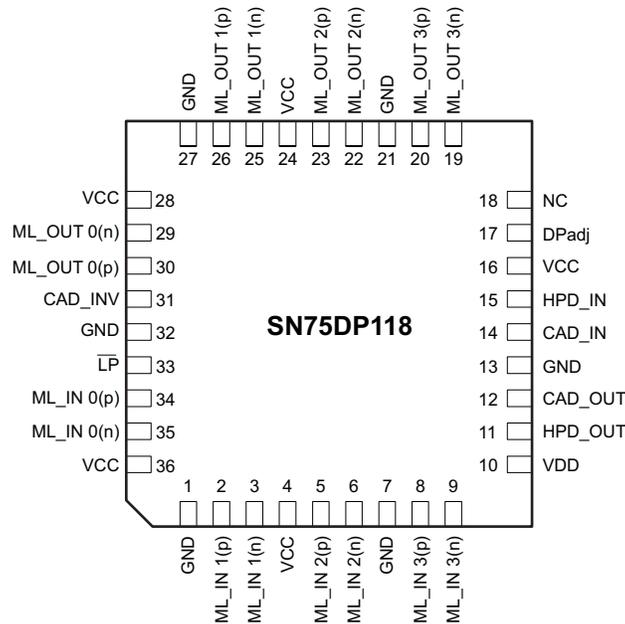


These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DATA FLOW BLOCK DIAGRAM



PACKAGE



PIN FUNCTIONS

PIN		I/O	DESCRIPTION
SIGNAL	NO.		
MAIN LINK INPUT PINS			
ML_IN 0	34, 35	I	DisplayPort Main Link Channel 0 Differential Input
ML_IN 1	2, 3	I	DisplayPort Main Link Channel 1 Differential Input
ML_IN 2	5, 6	I	DisplayPort Main Link Channel 2 Differential Input
ML_IN 3	8, 9	I	DisplayPort Main Link Channel 3 Differential Input
MAIN LINK OUTPUT PINS			
ML_OUT 0	30, 29	O	DisplayPort Main Link Port A Channel 0 Differential Output
ML_OUT 1	26, 25	O	DisplayPort Main Link Port A Channel 1 Differential Output
ML_OUT 2	23, 22	O	DisplayPort Main Link Port A Channel 2 Differential Output
ML_OUT 3	20, 19	O	DisplayPort Main Link Port A Channel 3 Differential Output
HOT PLUG DETECT PINS			
HPD_OUT	11	O	Hot Plug Detect Output to the DisplayPort Source
HPD_IN	15	I	Hot Plug Detect Input from the DisplayPort Connector
CABLE ADAPTER DETECT PINS			
CAD_OUT	12	O	Cable Adapter Detect Output to the DisplayPort Source
CAD_IN	14	I	Cable Adapter Detect Input from the DisplayPort Connector
CONTROL PINS			
$\overline{\text{LP}}$	33	I	Low Power Select Bar
CAD_INV	31	I	Output Port Priority selection
DP _{adj}	17	I	DisplayPort Main Link Output Gain Adjustment
NC	16		Not Connected
SUPPLY AND GROUND PINS			
VCC	4, 16, 24, 28, 36		Primary Supply Voltage
VDD	10		HPD and CAD Output Voltage
GND	1, 7, 13, 21, 27, 32		Ground

Table 1. Control Pin Lookup

SIGNAL	LEVEL ⁽¹⁾	STATE	DESCRIPTION
$\overline{\text{LP}}$	H	Normal Mode	Normal operational mode for device
	L	Low Power Mode	Device is forced into a Low Power state causing the outputs to go to a high impedance state. All other inputs are ignored.
CAD_INV	H	CAD Inverted	The CAD output logic is inverted from the CAD input
	L	CAD not Inverted	The CAD output logic follows the CAD input
DP _{adj}	4.53 k Ω	Increased Gain	Main Link DisplayPort Output will have an increased voltage swing
	6.49 k Ω	Nominal Gain	Main Link DisplayPort Output will have a nominal voltage swing
	10 k Ω	Decreased Gain	Main Link DisplayPort Output will have a decreased voltage swing

(1) (H) Logic High; (L) Logic Low

ORDERING INFORMATION

PART NUMBER	PART MARKING	PACKAGE ⁽¹⁾
SN75DP118RHHR	DP118	36-pin QFN Reel (large)
SN75DP118RHHT	DP118	36-pin QFN Reel (small)

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		VALUE	UNIT
Supply Voltage Range ⁽²⁾	V _{CC} , V _{DD}	-0.3 to 5.5	V
Voltage Range	Main Link I/O (ML_IN x, ML_OUT x) Differential Voltage	1.5	V
	HPD and CAD I/O	-0.3 to V _{CC} + 0.3	V
	Control I/O	-0.3 to V _{CC} + 0.3	V
Electrostatic discharge	Human body model ⁽³⁾	±12000	V
	Charged-device model ⁽⁴⁾	±1000	V
	Machine model ⁽⁵⁾	±200	V
Continuous power dissipation		See Dissipation Rating Table	

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, except differential voltages, are with respect to network ground terminal.

(3) Tested in accordance with JEDEC Standard 22, Test Method A114-B.

(4) Tested in accordance with JEDEC Standard 22, Test Method C101-A.

(5) Tested in accordance with JEDEC Standard 22, Test Method A115-A.

DISSIPATION RATINGS

PACKAGE	PCB JEDEC STANDARD	T _A < 25°C	DERATING FACTOR ⁽¹⁾ ABOVE T _A = 25°C	T _A = 85°C POWER RATING
36-pin QFN (RHH)	Low-K	759 mW	7.5 mW/°C	303 mW
	High-K	2127 mW	21.2 mW/°C	851 mW

(1) This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

THERMAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX ⁽¹⁾	UNIT
R _{θJB} Junction-to-board thermal resistance	4x4 Thermal vias under powerpad		28.11		°C/W
R _{θJC} Junction-to-case thermal resistance			32.77		°C/W
P _D Device power dissipation	L _P = 5.5 V; ML: V _{PP} = 1200 mV, 2.7 Gbps, PRBS; HPD_IN/CAD_IN/CAD_INV = 5.5 V; V _{CC} = 5.5 V, V _{DD} = 5.25 V; Temp = 85°C; DP _{adj} = 6.49 kΩ		240	280	mW
P _{SD} Device power dissipation under low power	L _P = 0V; HPD_IN/CAD_IN/CAD_INV = 5.5V; V _{CC} = 5.5V, V _{DD} = 5.2 V; Temp = 85°C; DP _{adj} = 6.49 kΩ			40	μW

(1) Maximum Rating is simulated under worse case condition.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply Voltage	4.5	5	5.5	V
V_{DD}	HPD and CAD Output reference voltage	1.62		5.25	V
T_A	Operating free-air temperature	0		85	°C
MAIN LINK DIFFERENTIAL PINS					
V_{ID}	Peak-to-peak input differential voltage	0.15		1.40	V
d_R	Data rate			2.7	Gbps
R_t	Termination resistance	45	50	55	Ω
$V_{O(term)}$	Output termination voltage	0		2	V
HPD, CAD, AND CONTROL PINS					
V_{IH}	High-level input voltage	2		5.5	V
V_{IL}	Low-level input Voltage	0		0.8	V

DEVICE POWER

The SN75DP118 is designed to operate off of a single 5V supply.

ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{CC}	Supply current $\overline{LP} = 5.5\text{ V}$; ML: $V_{PP} = 1200\text{ mV}$, 2.7 Gbps, PRBS; HPD_IN/CAD_IN/CAD_INV = 5.5 V; $V_{CC} = 5.5\text{ V}$, $V_{DD} = 5.25\text{ V}$; Temp = 85°C; $DP_{adj} = 6.49\text{ k}\Omega$		50	55	mA
I_{DD}	Supply current $V_{DD} = 5.5\text{ V}$		0.1	2	mA
I_{SD}	Shutdown current $\overline{LP} = 0\text{ V}$; HPD_IN/CAD_IN/CAD_INV = 5.5 V; $V_{CC} = 5.5\text{ V}$, $V_{DD} = 5.25\text{ V}$; Temp = 85°C; $DP_{adj} = 6.49\text{ k}\Omega$		4	10	μA

HOT PLUG AND CABLE ADAPTER DETECT

The SN75DP118 has a built in level shifter for the HPD and CAD outputs. The output voltage level of the HPD and CAD pins is defined by the voltage level of the VDD pin. The state of the HPD pin will also set the active state of the device. If HPD is low the device will enter low power mode. Once HPD goes high, the device will come out of low power mode and enter active mode. If HPD goes LOW for a period of time exceeding $t_{T(HPD)}$, the device will enter the low power mode.

ELECTRICAL CHARACTERISTICS

over recommended operating (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT				
V_{OH5}	High-level output voltage	$I_{OH} = -100\ \mu\text{A}$, $V_{DD} = 5\text{ V}$	4.5	5	V				
$V_{OH3.3}$						$I_{OH} = -100\ \mu\text{A}$, $V_{DD} = 3.3\text{ V}$	3	3.3	V
$V_{OH2.5}$						$I_{OH} = -100\ \mu\text{A}$, $V_{DD} = 2.5\text{ V}$	2.25	2.5	V
$V_{OH1.8}$						$I_{OH} = -100\ \mu\text{A}$, $V_{DD} = 1.8\text{ V}$	1.62	1.8	V
V_{OL}	Low-level output voltage	$I_{OH} = 100\ \mu\text{A}$	0	0.4	V				
I_H	High-level input current	$V_{IH} = 2\text{ V}$, $V_{CC} = 5.5\text{ V}$	-10	10	μA				
I_L	Low-level input current	$V_{IL} = 0.8\text{ V}$, $V_{CC} = 5.5\text{ V}$	-10	10	μA				

SWITCHING CHARACTERISTICS

over recommended operating (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{PD(CAD)}$	Propagation delay	$V_{DD} = 5\text{ V}$		20	30	ns
$t_{PD(HPD)}$	Propagation delay	$V_{DD} = 5\text{ V}$		70	110	ns
$t_{T(HPD)}$	HPD logic switch time	$V_{DD} = 5\text{ V}$	200		400	ms
$t_{M(HPD)}$	Minimum output pulse duration	$V_{DD} = 5\text{ V}$	100			ns
$t_{Z(HPD)}$	Low power to high-level propagation delay	$V_{DD} = 5\text{ V}$		70	110	ns

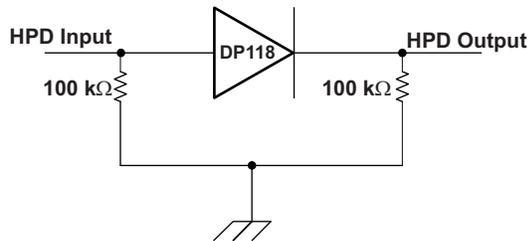


Figure 1. HPD Test Circuit

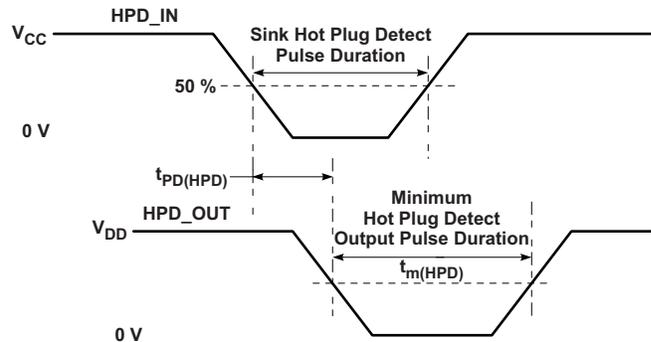


Figure 2. HPD Timing Diagram #1

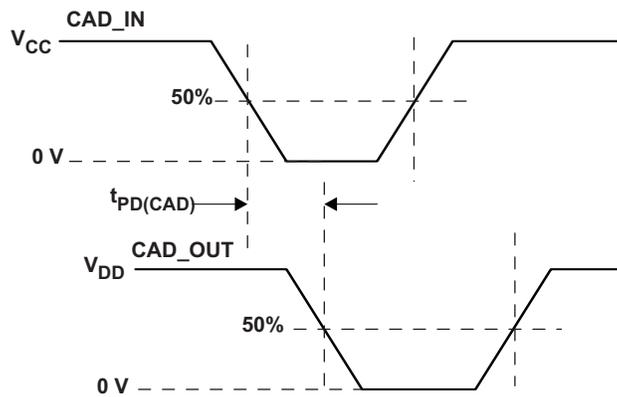


Figure 3. CAD Timing Diagram

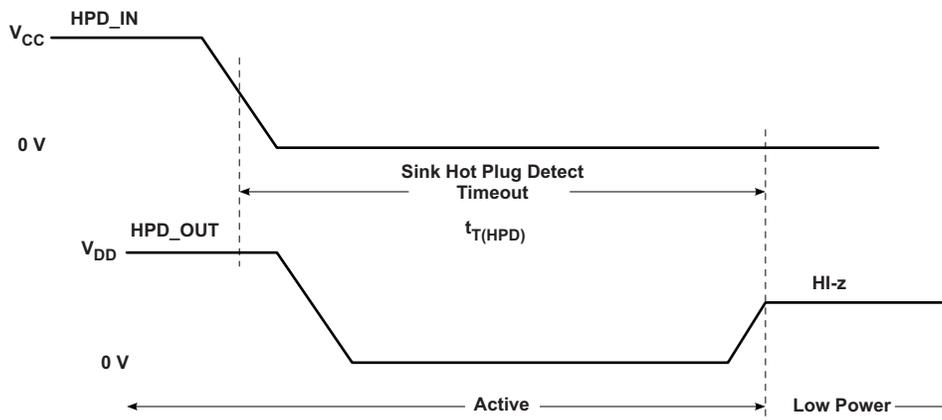


Figure 4. HPD Timing Diagram Number 2

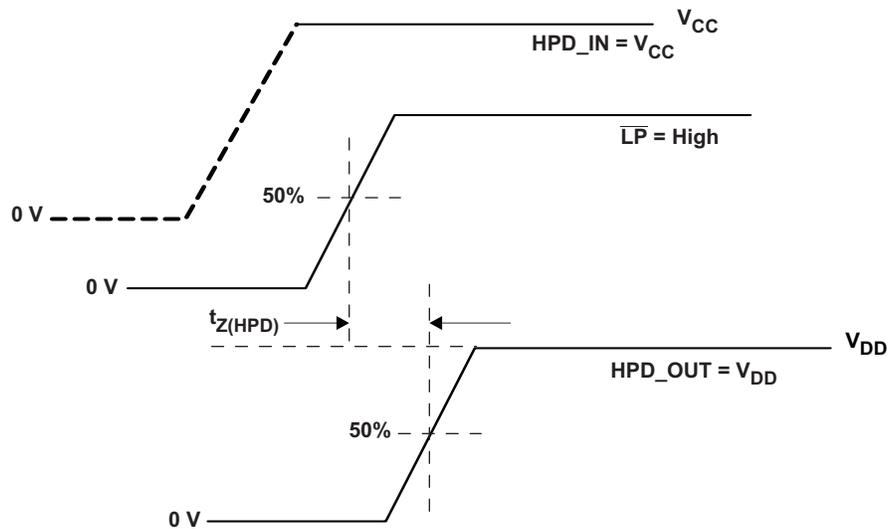


Figure 5. HPD Timing Diagram Number 3

MAIN LINK PINS

The main link I/O of the SN75DP118 is designed to track the magnitude and frequency characteristics of the input waveform and replicate them on the output. A feature has also been incorporated in the SN75DP118 to either increase or decrease the output amplitude via the resistor connected between the DP_{adj} pin and ground.

ELECTRICAL CHARACTERISTICS

over recommended operating (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$\Delta V_{I/O(2)}$	Difference between input and output voltages ($V_{OD} - V_{ID}$)	$V_{ID} = 200 \text{ mV}$, DP _{adj} = 6.5 k Ω	0	30	60	mV
$\Delta V_{I/O(3)}$		$V_{ID} = 300 \text{ mV}$, DP _{adj} = 6.5 k Ω	-24	11	36	
$\Delta V_{I/O(4)}$		$V_{ID} = 400 \text{ mV}$, DP _{adj} = 6.5 k Ω	-45	-15	15	
$\Delta V_{I/O(6)}$		$V_{ID} = 600 \text{ mV}$, DP _{adj} = 6.5 k Ω	-87	-47	-22	
R _{INT}	Input termination impedance		45	50	55	Ω
V _{Iterm}	Input termination voltage		0		2	V

SWITCHING CHARACTERISTICS

over recommended operating (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{R/F(DP)}	Output edge rate (20% - 80%)	Input edge rate = 80 ps (20% - 80%)		115		ps
t _{PD}	Propagation delay time	F = 1MHz, V _{ID} = 400 mV	200	240	280	ps
t _{SK(1)}	Intra-pair skew	F = 1MHz, V _{ID} = 400 mV			20	ps
t _{SK(2)}	Inter-pair skew	F = 1MHz, V _{ID} = 400 mV			40	ps
t _{DPJIT(PP)}	Peak-to-peak output residual jitter	dR = 2.7Gbps, V _{ID} = 400 mV, PRBS7		25	35	ps

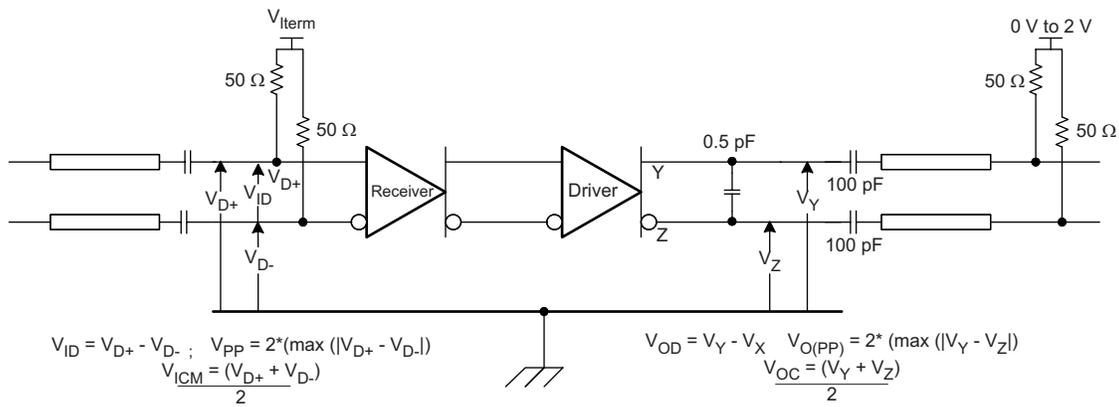


Figure 6. Main Link Test Circuit

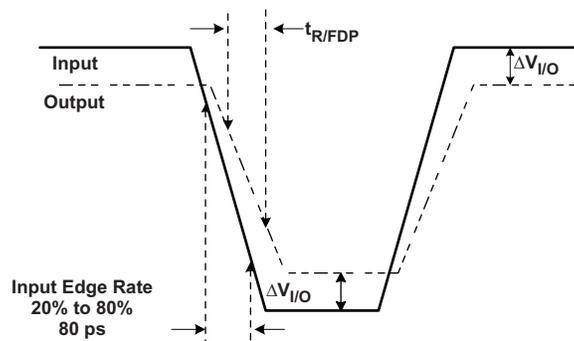


Figure 7. Main Link $\Delta V_{I/O}$ and Edge Rate Measurements

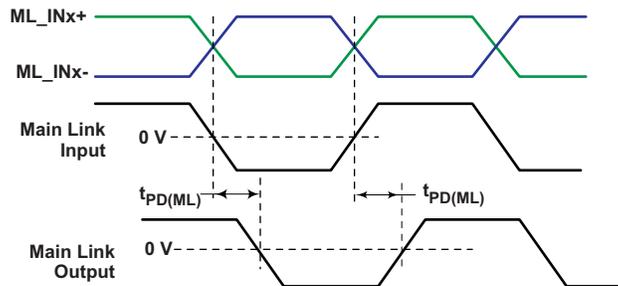


Figure 8. Main Link Delay Measurements

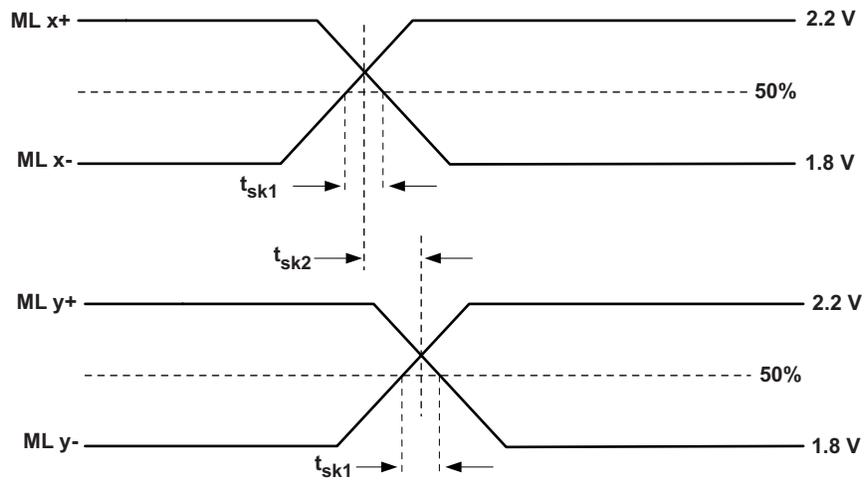


Figure 9. Main Link Skew Measurements

TYPICAL CHARACTERISTICS

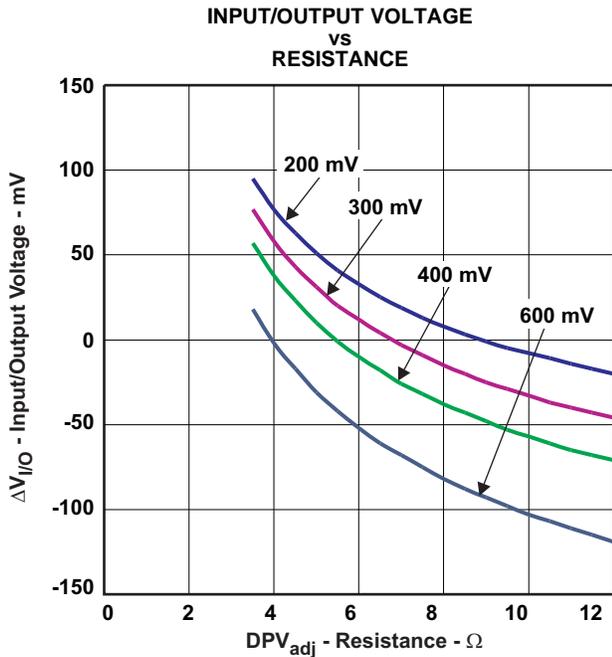


Figure 10.

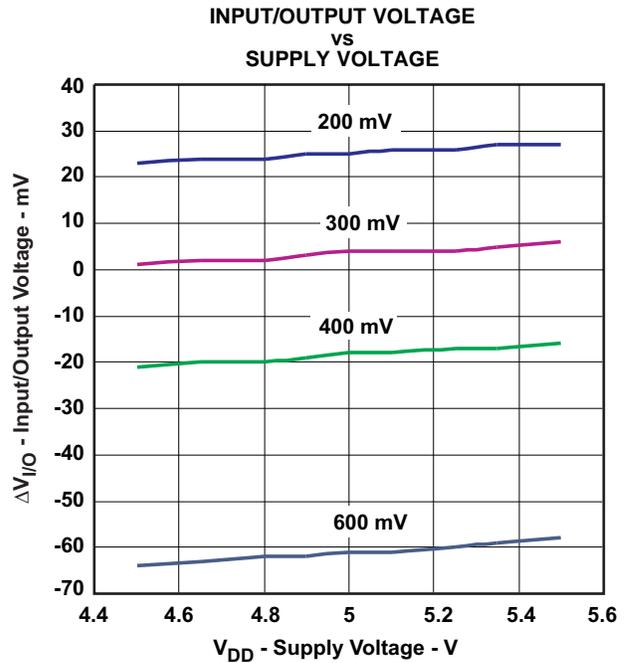


Figure 11.

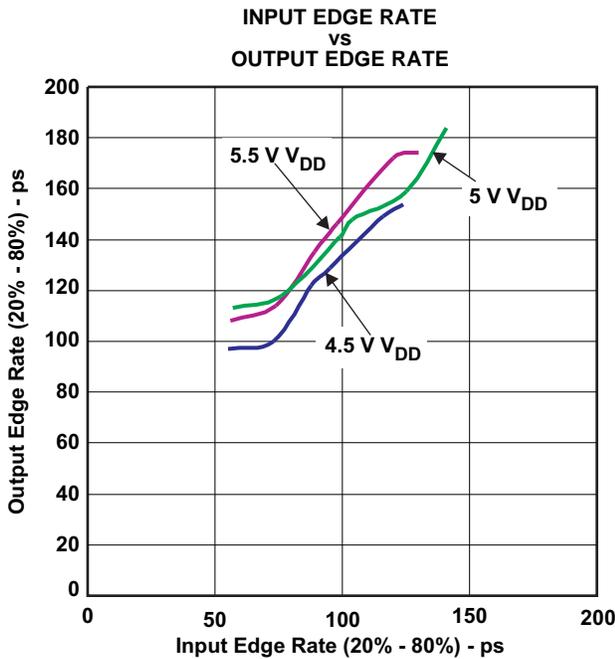


Figure 12.

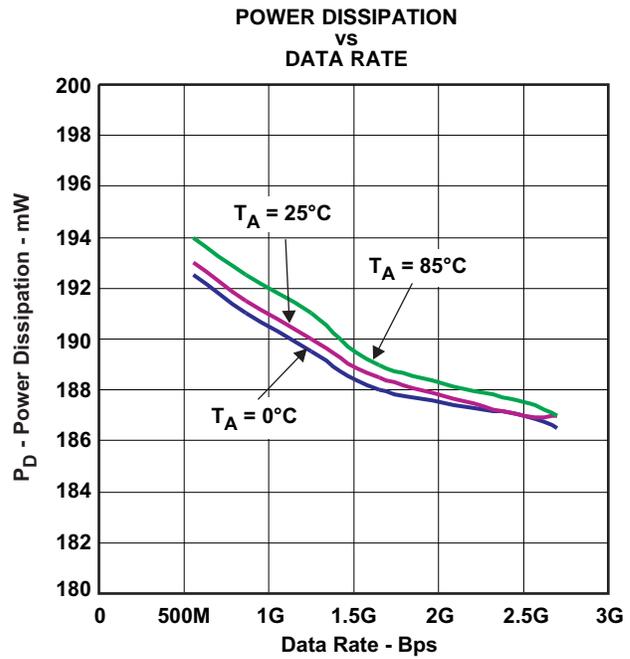


Figure 13.

APPLICATION INFORMATION

Power Logic

The power logic of the SN75DP118 is tied to the state of the HPD input pin as well as the low power pin. When HPD_IN is LOW the SN75DP118 enters the low power state. In this state the outputs are high impedance and the device shuts down to optimize power conservation. When HPD_IN goes high the device enters the normal operational state.

Several key factors were taken into consideration with this digital logic implementation of channel selection, as well as HPD repeating. This logic is described in the following scenarios.

Scenario 1. Low Power State to Active State:

- There are two possible cases for this scenario depending on the state of the low power pin.
 - Case one: In this case HPD_IN is initially LOW and the low power pin is also LOW. In this initial state the device is in a low power mode. Once the HPD input goes to a HIGH state the device remains in the low power mode, with both the main link and auxiliary I/O in a high impedance state (Figure 14).
 - Case two: In this case HPD_IN is initially LOW and the low power pin is HIGH. In this initial state the device is in a low power mode. Once the HPD input goes to a HIGH state the device comes out of the low power mode and enters active mode, enabling the main link and auxiliary I/O. The HPD output to the source is enabled and follows the logic state of the input HPD (Figure 15). This is specified as $t_{Z(HPD)}$.

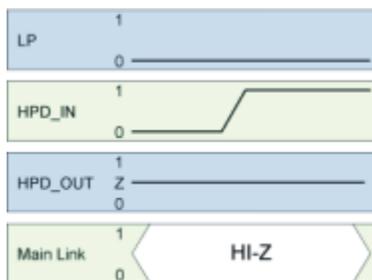


Figure 14.

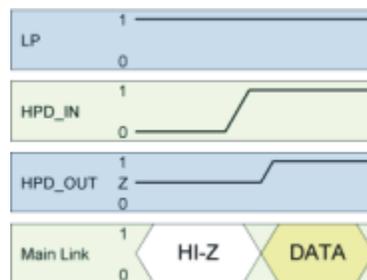


Figure 15.

Scenario 2. HPD Changes:

- In this case the HPD input is initially HIGH. The HPD output logic state follows the state of the HPD input. If the HPD input pulses LOW, as may be the case if the sink device is requesting an interrupt, the HPD output to the source will also pulse Low for the same duration of time with a slight delay (Figure 16). The delay of this signal through the SN75DP118 is specified as $t_{PD(HPD)}$. If the duration of the LOW pulse is less than $t_{M(HPD)}$ it may not be accurately repeated to the source. If the duration of the LOW pulse exceeds $t_{T(HPD)}$ the device determines that an unplug event has occurred and enters the low power state (Figure 17). Once the HPD input goes high again the device returns to the active state as indicated in scenario 1.

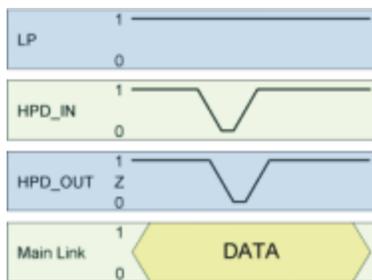


Figure 16.

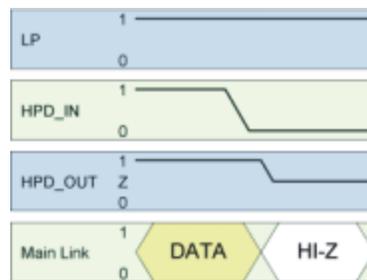


Figure 17.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN75DP118RHHR	Active	Production	VQFN (RHH) 36	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	0 to 85	DP118
SN75DP118RHHR.B	Active	Production	VQFN (RHH) 36	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	0 to 85	DP118
SN75DP118RHHT	Active	Production	VQFN (RHH) 36	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	0 to 85	DP118
SN75DP118RHHT.B	Active	Production	VQFN (RHH) 36	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	0 to 85	DP118

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75DP118RHHR	VQFN	RHH	36	2500	330.0	16.4	6.3	6.3	1.1	12.0	16.0	Q2
SN75DP118RHHT	VQFN	RHH	36	250	180.0	16.4	6.3	6.3	1.1	12.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75DP118RHHR	VQFN	RHH	36	2500	356.0	356.0	35.0
SN75DP118RHHT	VQFN	RHH	36	250	210.0	185.0	35.0

GENERIC PACKAGE VIEW

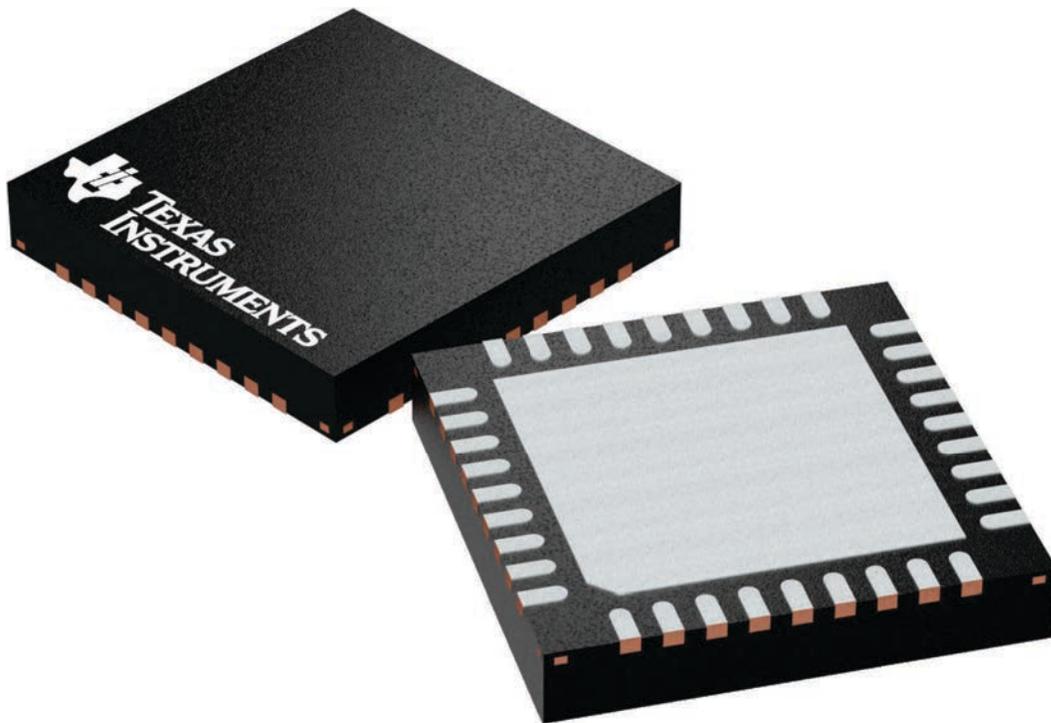
RHH 36

VQFN - 1 mm max height

6 x 6, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



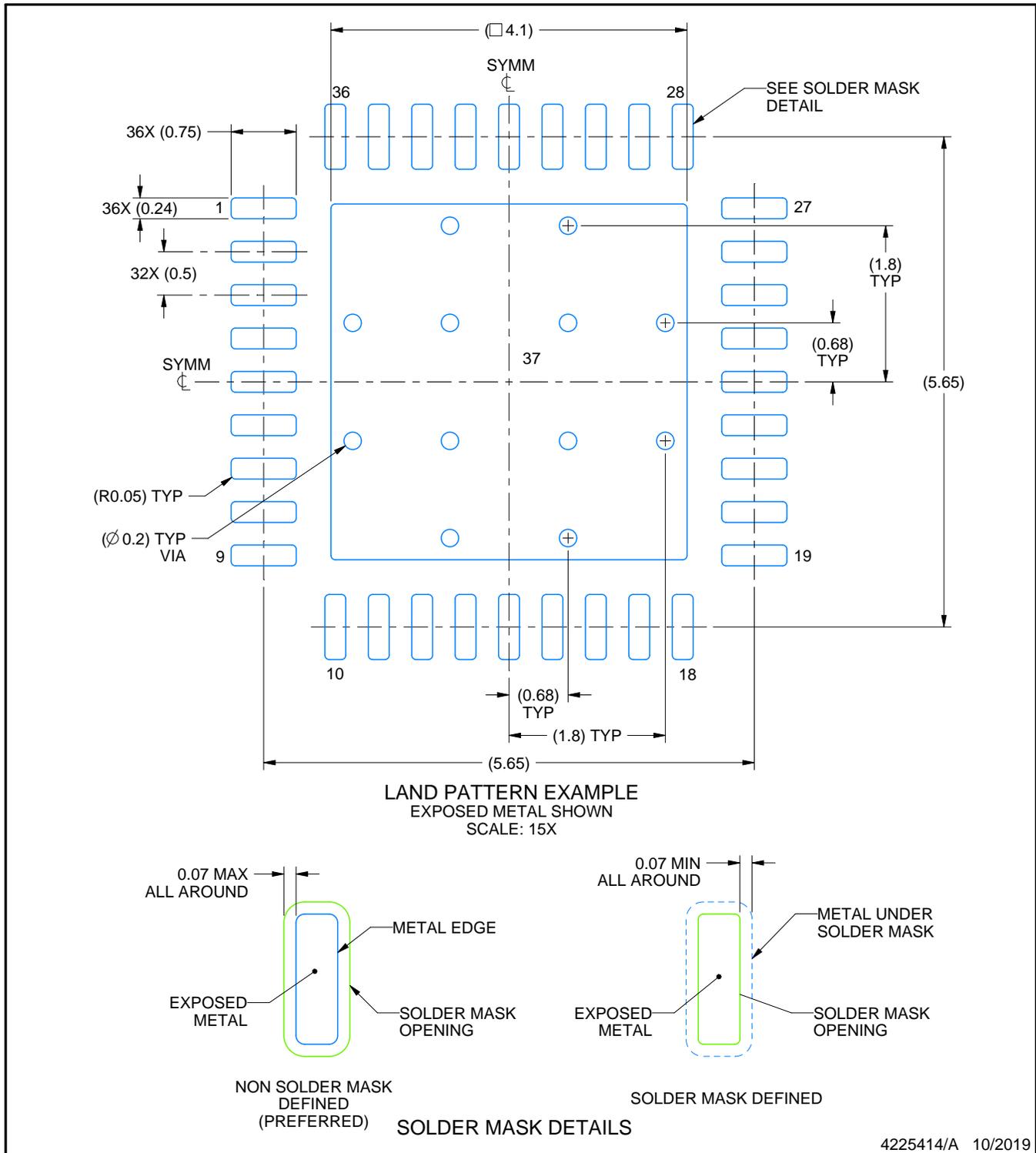
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EXAMPLE BOARD LAYOUT

RHH0036B

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



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NOTES: (continued)

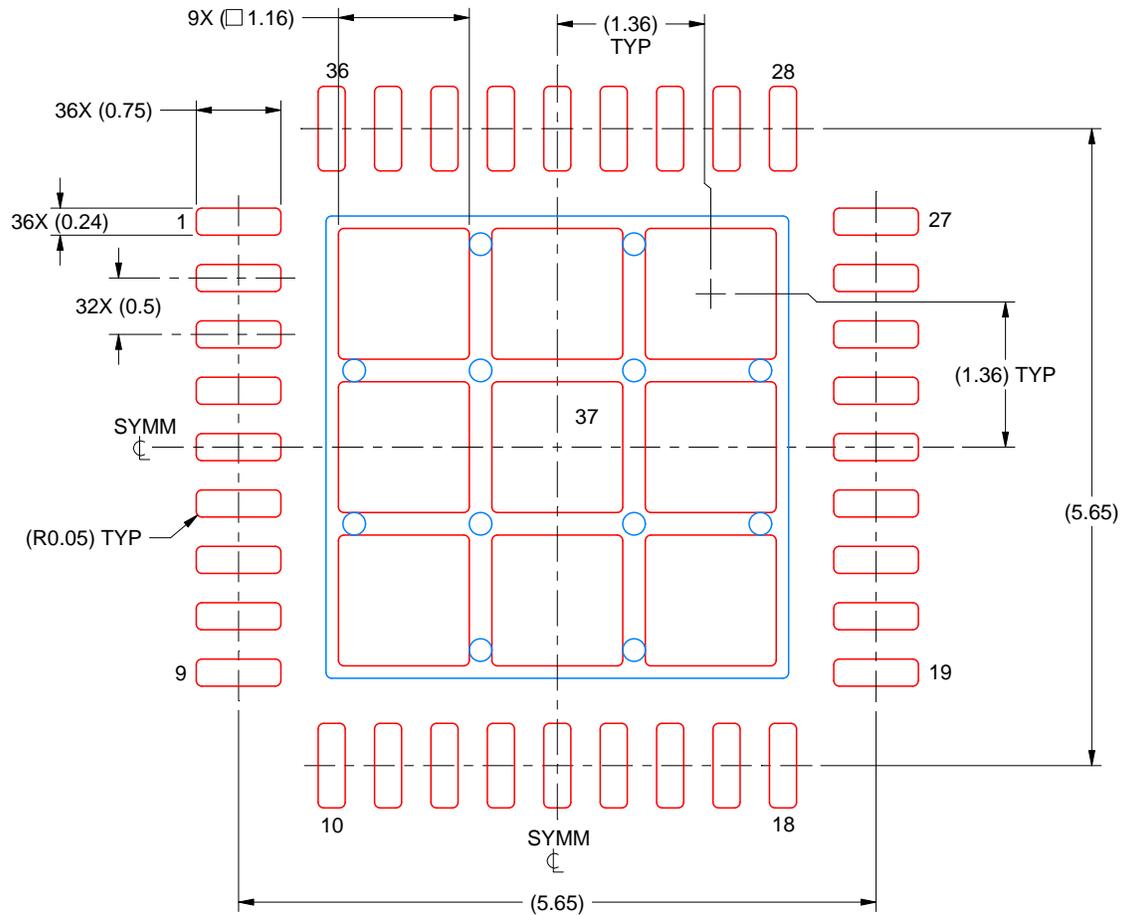
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RHH0036B

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 15X

EXPOSED PAD 37
72% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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